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	AB2	2002/0098617 A1		Lee et al.	438		106	09/18/2001			
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	AE2	5,801,432	09/1998	Rostoker et al.							
	AF2	5,953,589	09/1999	Shim et al.							
	AG2	6,069,407	05/2000	Hamzehdoost							
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	AC2	10/284,366	8/7/2003	Zhao et al.			10/31/2002
	AD2	5,173.766	12/22/1992	Long et al.			0625/1990
	AE2	5,216,278	6/1/1993	Lin et al.			03/02/1992
	AF2	5,285,352	2/8/1994	Pastore et al.			07/15/1992
	AG2	5,552,635	9/3/1996	Kim et al.			1/10/1995
	AH2	5,866,949	02/02/1999	Schueller			10/8/1997
	Al2	5,949,137	09/07/1999	Domadia et al.			09/26/1997
	AJ2	5,986,340	11/16/1999	Mostafazadeh et al.			5/2/1996
مخبن	AK2	6,084,297	7/4/2000	Brooks et al.			9/3/1998
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(AB4	6,462.274 B1	10/8/2002	Shim et al.			10/20/1999
	AC4	6,528,892,B2	3/4/2003	Caletka et al.			6/5/2001
	AD4	6,563,712 B2	5/13/2003	Akram et al.			5/16/2002
	AE4	6,011,694	1/4/2000	Hirakawa			8/1/1997
	AF4	5,541,450	7/30/1996	Jones et al.			11/2/1994
	AG4	6,583,516 B2	6/24/2003	Hashimoto			11/1/2001
	AH4	6,552,266 B2	4/22/2003	Carden et al.			1/26/2001
	Al4	6,002,147	12/14/1999	lovdalsky et af.			9/26/1996
	AJ4	6,060,777	5/9/2000	Jamieson et al.			7/21/1998
MO	AK4	5,920,117	7/6/1999	Sono et al.			3/18/1997
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400	AA5	5,650,659	7/22/1997	Mostafazadeh et al.			8/4/1995
(AB5	5,977,626	11/2/1999	Wang et al.			8/12/1998
	AC5	5,294,826	3/15/1994	Marcantonio et al.			4/16/1993
	AD5	6,552,428 B1	4/22/2003	Huang et al.		10	10/12/1999
	AE5	5,208,504	05/04/1993	Parker et al.		2	712/28/1990
	AF5	5,366,589	11/22/1994	Chang		8 9	14/16/1993
	AG5	5,394,009	02/28/1995	L00		2.0	:07/30/1993
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	AD1	09/9	84,259			Zhac	et al.				10/29/2001
	AE1	09/9	97,272			Zhac	et al.				11/30/2001
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	AQ	1	Andrews, M., "Trends in Ball Grid Array Technology," Ball Grid Array National Symposium, March 29-30, 1995, Dallas, Texas, 10 pages.								
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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Page 6 of 20 APPLICATION NO. ATTY, DOCKET NO. 1875.0210000 09/783,034 FORM PTO-1449 APPLICANT Khan et al SUPPLEMENTAL INFORMATION DISCLOSURE GROUP FILING DATE 2001 2826 February 15. **U.S. PATENT DOCUMENTS EXAMINER CLASS** SUB-FILING DATE INITIAL DOCUMENT DATE NAME NUMBER **CLASS** AA6 AB6 AC₆ AD6 AE6 AF6 AG6 AH₆ Al6 **FOREIGN PATENT DOCUMENTS EXAMINER** DOCUMENT NUMBER COUNTRY **CLASS** SUB-TRANSLATION INITIAL DATE **CLASS** AJ6 No AK6 Yes No AL6 Yes No AM6 Yes No OTHER (Including Author, Title, Date, Pertinent Pages, etc.) Freyman, B. et al., "Surface Mount Process Technology for Ball Grid Array Packaging", Surface Mount International Conference Proceedings, Surface Mount International, August 29-September 2, 1993, San Jose, California, pp. 81-85. AN 6 Freyman, B. et al., "The Move to Perimeter Plastic BGAs", Surface Mount International Conference Proceedings, San Jose, CA, August 29-31, 1995, pp. 373-382. AO <u>6</u> Freyman, B., "Trends in Plastic BGA Packaging," Ball Grid Array National Symposium, Dallas, Texas, March 29-30, 1995, 45 pages. ΑP 6 Gilleo, K., "Electronic Polymers: Die Attach and Oriented Z-Axis Films", Advanced Packaging, IHS Publishing Group, September/October 1994, Vol. 3, No. 5, pp. 37-38, 40 and 42. AQ <u>6</u> Guenin, B. et al., "Analysis of a Thermally Enhanced Ball Grid Array Package", IEEE Transactions on Components, Packaging, and Manufacturing Technology, Part A, IEEE Components, Packaging, and Manufacturing Technology Society, December 1995, Vol. 18, No. 4, pp. 749-757. <u>6</u> EXAMINER DATE CONSIDERED

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No OTHER (Including Author, Title, Date, Pertinent Pages, etc.) Holden, H., "The Many Techniques of Small Via Formation for Thin Boards", The Institute for Interconnecting and Packaging Electronic Circuits Ball Grid Array National Symposium, San Diego, CA, January 18-19, 1996, pp. 1-7. AN 8 AN Houghten, J., "New Package Takes On QFPs", Advanced Packaging, IHS Publishing Group, Winter 1993, Vol. 2, No. 1, pp. 38-39. AO 8 "How To Give Your BGAs A Better Bottom Line.", Advanced Packaging, IHS Publishing Group, AP <u>8</u> January/February 1995, page unknown. Huang, W. and Ricks, J., "Electrical Characterization of PBGA for Communication Applications by Simulation and Measurement", National Electronic Packaging and Production Conference West '95, February 26-March 2, 1995, Anaheim, California, pp. 300-307. AQ 8 Hundt, M. et al., "Thermal Enhancements of Ball Grid Arrays", National Electronic Packaging and Production Conference West '95, Reed Exhibition Companies, Anaheim, CA, February 25-29, 1996, pp. 702-711. 8 AR

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Page 19 of 20 ATTY. DOCKET NO. APPLICATION NO. 1875.0210000 09/783,034 FORM PTO-1449 APPLICANT Khan et al SUPPLEMENTAL INFORMATION DISCLOSUR FILING DATE GROUP February 15, 2001 2826 **U.S. PATENT DOCUMENTS EXAMINER** DATE NAME CLASS SUB-FILING DATE INITIAL DOCUMENT NUMBER CLASS **AA19** AB19 AC19 AD19 AE19 AF19 AGJ9 AH19 AI19 **FOREIGN PATENT DOCUMENTS EXAMINER** DOCUMENT NUMBER DATE COUNTRY **CLASS TRANSLATION** INITIAL SUB-CLASS AJ19 Yes No AK/19 **Yes** No AL19 Yes No AM19 Yes No OTHER (Including Author, Title, Date, Pertinent Pages, etc.) Yip, W.Y., "Package Characterization of a 313 Pin BGA", National Electronic Packaging and Production Conference West '95, Reed Exhibition Companies, February 26-March 2, 1995, Anaheim, California, pp. 1530-1541. ΑN 19 MA Zamborsky, E., "BGAs in the Assembly Process", Circuits Assembly, February 1995, Vol. 6, No. 2, pp. 60, 62-64. ΑO <u> 19</u> Zimerman, M., "High Performance BGA Molded Packages for MCM Application", Surface Mount International Conference Proceedings, Surface Mount International, August 28-September1, 1994, San Jose, California, pp. 175-180. ΑP 19 Zweig, G., "BGAs: Inspect the Process, Not the Product", Electronic Packaging & Production (Special Supplement), Cahners Publishing Company, August 1994 (Supplement), p. 41. AQ 19 Houghten, J.L., "Plastic Ball-Grid Arrays Continue To Evolve", Electronic Design, February 6, 1995, pp. #41-146. AR 19 EXAMINER DATE CONSHIDERED

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